Continued Growth and Benefits of CMP Process Development Through CNSE

NCCAVS
CMP USERS GROUP
2013 Spring Meeting
College of NanoScale Science & Engineering (CNSE)

Frank Tolic

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College of Nanoscale Science and Engineering
Albany, NY



CNSE

The College of Nanoscale Science and Engineering (CNSE) of the State University of New York (SUNY) is a global education, research, development and technology deployment resource dedicated to preparing the next generation of scientists and researchers in nanotechnology.

By leveraging its resources in partnership with business and government, CNSE supports accelerated high technology education and commercialization, and seeks to create jobs and economic growth for nanotechnology-related industries.

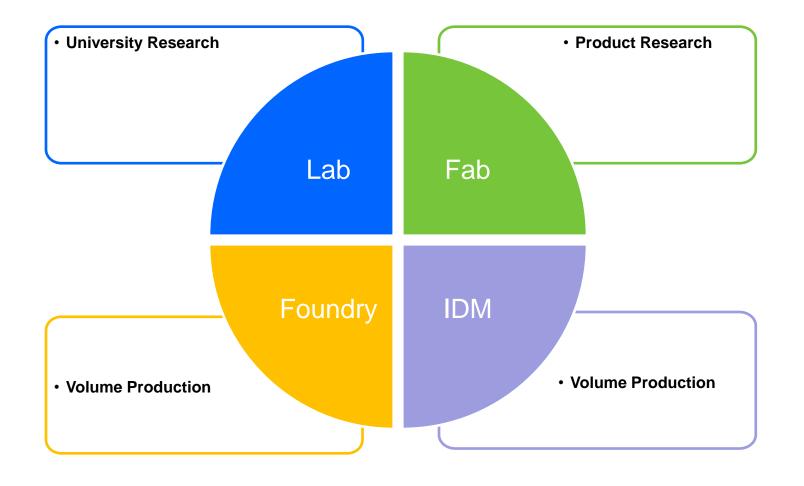


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- CNSE CMP Center of Excellence (CoE)
- Faculty Research
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- Conclusion

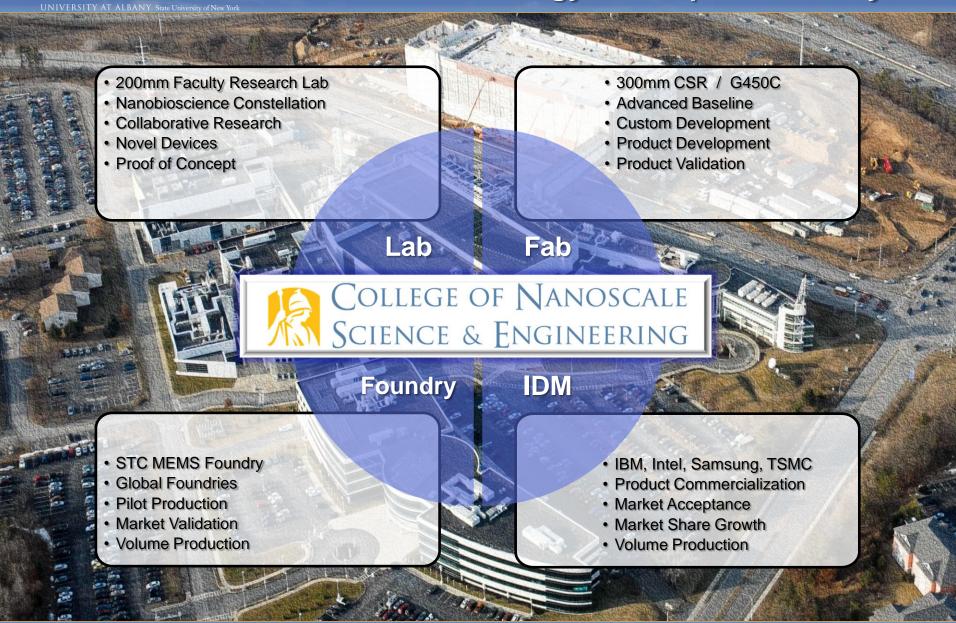


Traditional Product Life Cycle Eco System





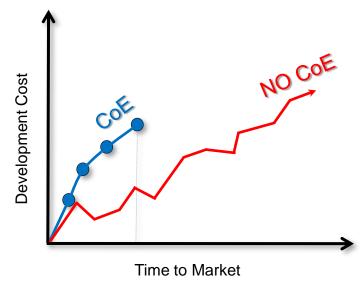
CNSE Nanotechnology Development Eco System





CNSE CMP CoE Development Service

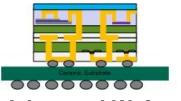
- Center of Excellence (CoE) is a proven CNSE methodology currently used successfully by CNSE Equipment Makers and Others
- Benefits to Customer are:
 - Advanced technology platform for quick development
 - Minimize cycles of learning
 - Access to customers and their needs
 - Strategy for market share capture
 - Maximize research and development ROI





Unlock your development success with CNSE CoE











CNSE Faculty Advance Research



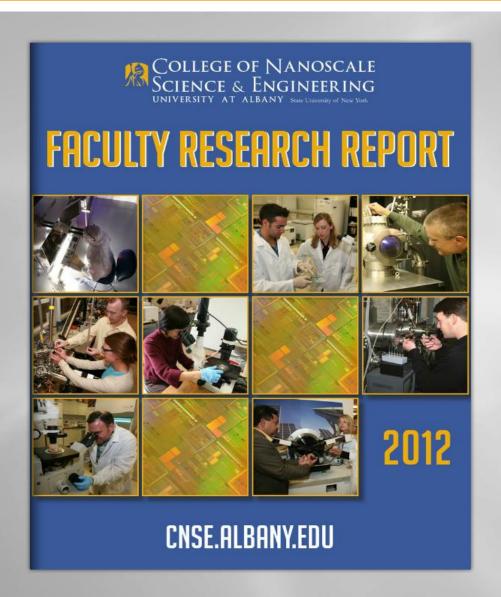
Dr. Sara Brenner: Dr. Brenner is a preventive medicine and public health physician serving as the CNSE Assistant Vice President for NanoHealth Initiatives and an Assistant Professor of Nanobioscience. She is leading health and safety research initiatives related to nanoparticle and nanomaterial exposures in the workplace and also serves as Chair of the steering committee for the CNSE-ISMI NanoHealth and Safety Center. Her research team incorporates theory from many disciplines to advance risk assessment and reduction strategies for occupational exposures, monitoring of materials that may impact population health and public safety, and the development of industrial practice standards for product safety.



Dr. James Castracane: Dr. Castracane is Professor (Founding Faculty) and Head of the Nanobioscience Constellation in CNSE. His research interests encompass fundamental materials science, 3D integration, nanobioscience, optoelectronics, MEMS, and emerging fields such as molecular electronics and spintronics. Under Dr. Castracane's guidance, CNSE has assembled a multi-faceted Nanobioscience program. He has received research funding from numerous Federal agencies including NIH, NSF, DOD, DOE, DARPA, and NASA as well as a significant portfolio of State and corporate sponsors. His publication record spans over 100 articles, numerous invited or keynote presentations and 14 patents issued/pending.



Dr. James Lloyd: Dr. Lloyd's research has been into physical modeling of materials degradation and designing testing procedures that provide the necessary tools to predict lifetime and demonstrate reliability through accelerated tests. This includes both developing theories and the related supporting experiments to avoid the sin of "overstressing" where failure is experienced but under conditions that are irrelevant to real life. In addition, reliability testing must be performed in a way that will enable data that can predict reliability over decades to be obtained in as short a time as possible, at most weeks and preferably hours. This requires the use of "Accelerated Testing" where failure mechanisms are exercised at elevated stress levels and the data obtained is extrapolated to more gentle use conditions.



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Search: Faculty Report



CNSE CMP Engagement Levels

Level 1 \$200K - \$500K

- Blanket Wafers
- Tool Access
- Structure wafers

Level 2 \$500K - \$800K

- Module Wafers
- Days/Yr. Tool Access
- Dedicated Engr.
- WIP allocation

Level 3 \$800K - \$1.2M

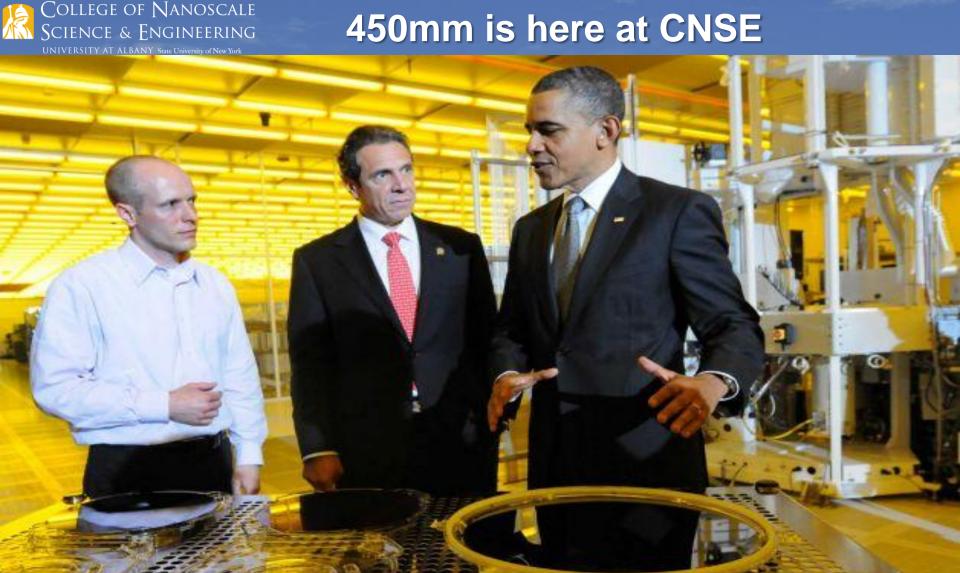
- Full Flow CMOS
- Electrical Results
- Baseline Benchmark
- Defect FA

CoE > \$1.2M

- Sub 20nm Wafers
- Customer Engagement
- Joint Development

Strengths:

- > Strong enabling relationships with technology leading IDM and OEM partners
- > IP Independence
- > Access to advanced lithography, films, metals, etch, and other novel process capability
- > Technology capable infrastructure and research expertise
- > FEOL & BEOL electrical test-mask and physical structures at the <28nm technology node
- Advanced sub 20nm wafers













CMP Process Development – Defect Reduction

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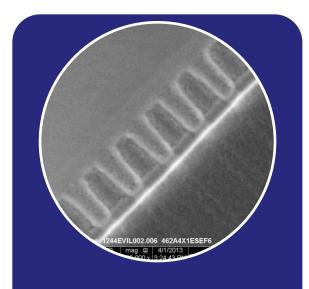
Tricia E Burroughs

CNSE Engineering Research & Development, CMP

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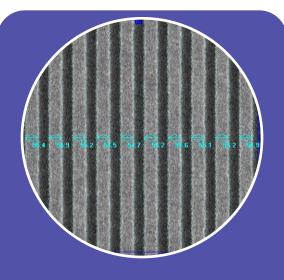


BEOL Development Masks



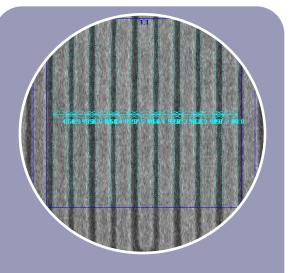
Empire II

28nm node = 32nm line



Empire

45nm node = 42nm line

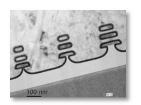


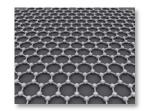
Intrepid

14nm node = 28nm line

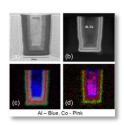


CNSE Technology Roadmap













MRAM RRAM

Photonics

Derivatives

Exploratory

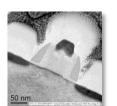
Nanowires

III-V

Graphene

STT Logic





65nm LP CMOS

28nm LP CMOS

Prototyping

Development

22nm FinFET

14nm FinFET 10nm FinFET 7nm TBD

2009

2010

2011

2012

2013

2014

2015

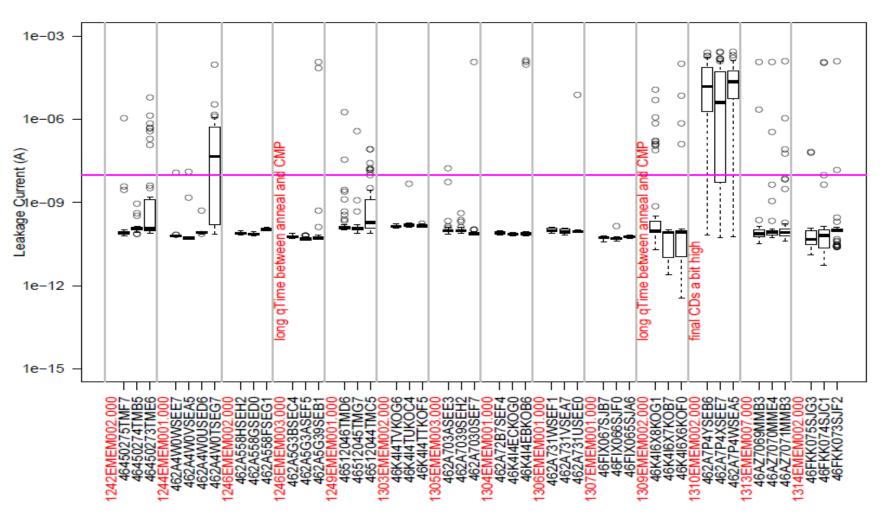
2016

2017

2018

Empire – Parametric Trend Charts

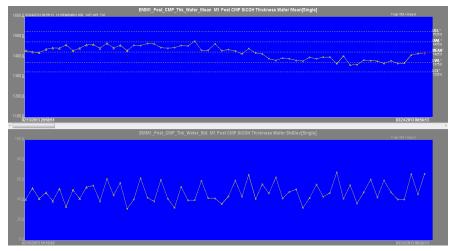
COM1B~M1~Ileak_P2_4 Comb - 48nm 1:1

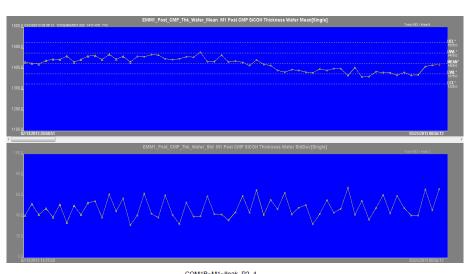


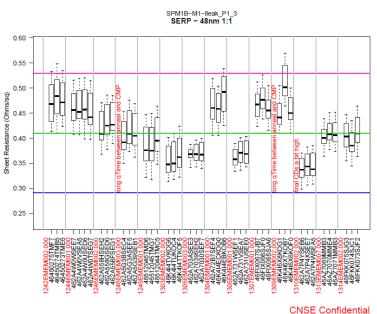
CNSE Confidential

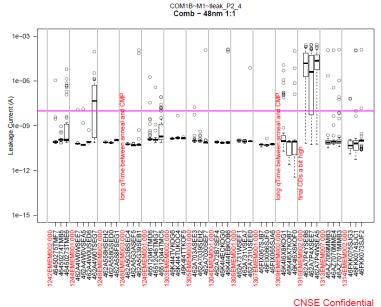


Empire – Parametric Trend Charts





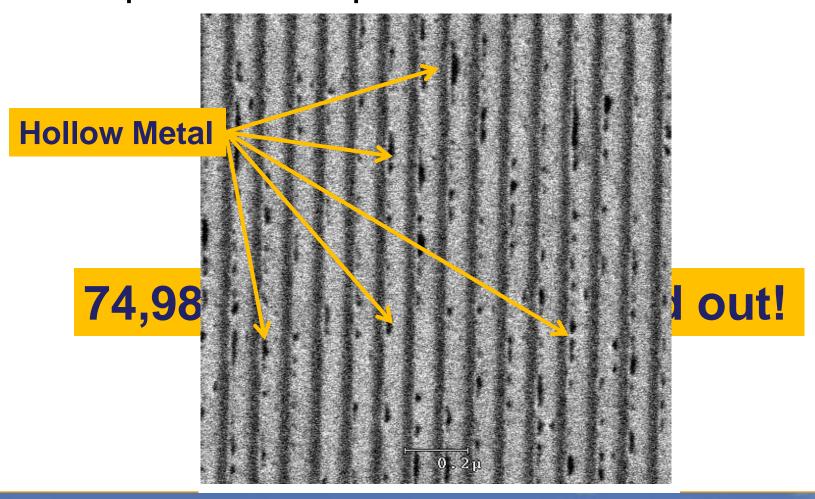






Empire – Defect Reduction

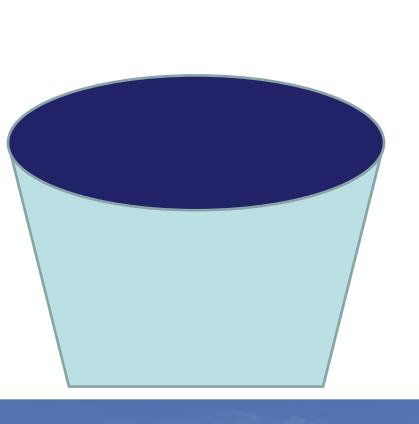
Set-up Defect Inspection & Review

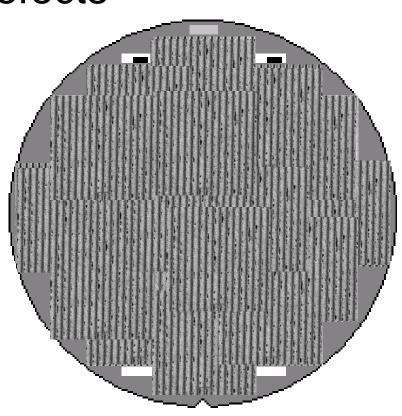




Empire - PLY Issue

Binning of Nuisance Defects

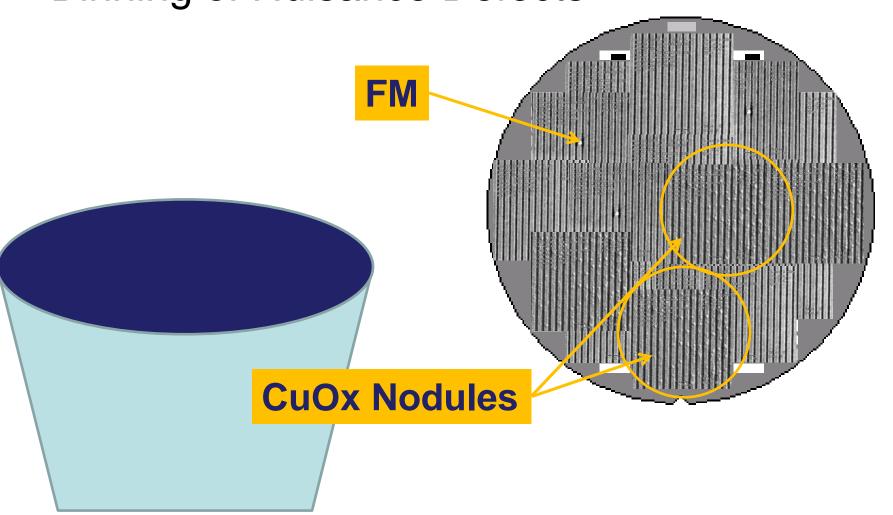






Empire - PLY Issue

Binning of Nuisance Defects





Empire – CuOx Nodules

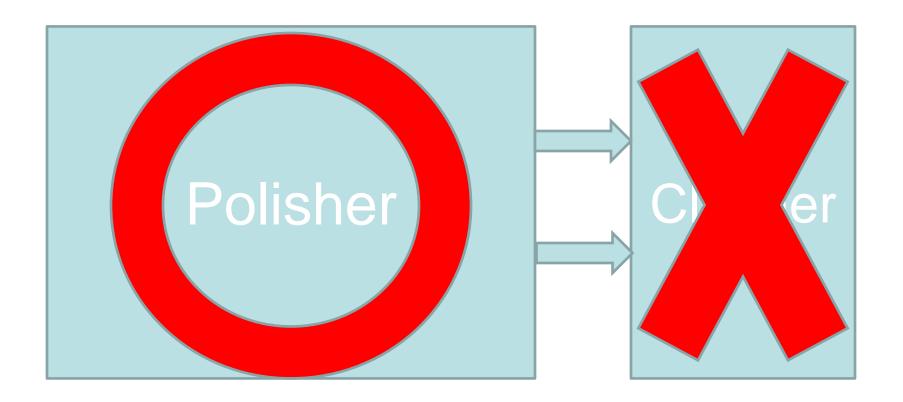
DIW dip test of Cu produces CuOx nodules

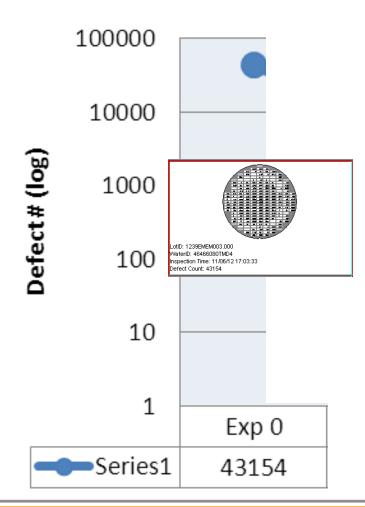


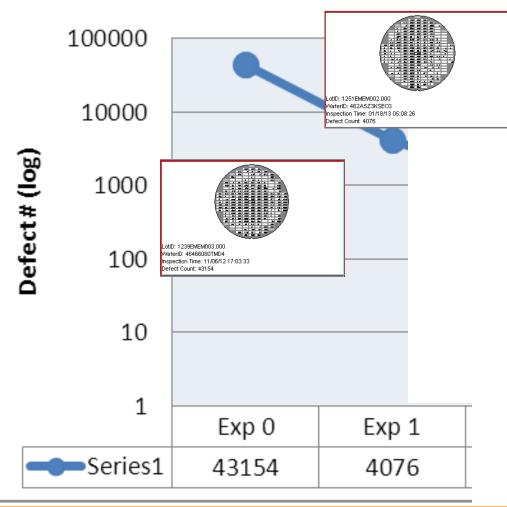
Incomplete passivation of Cu surface

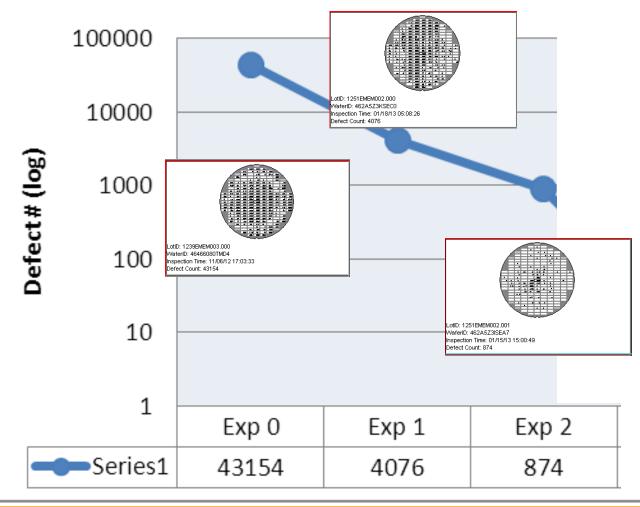
Empire - Passivation

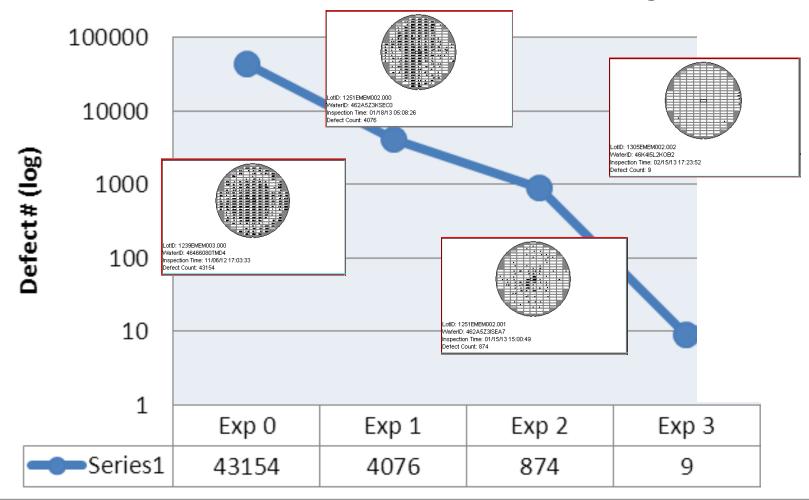
Picture of Cu Ox & FM

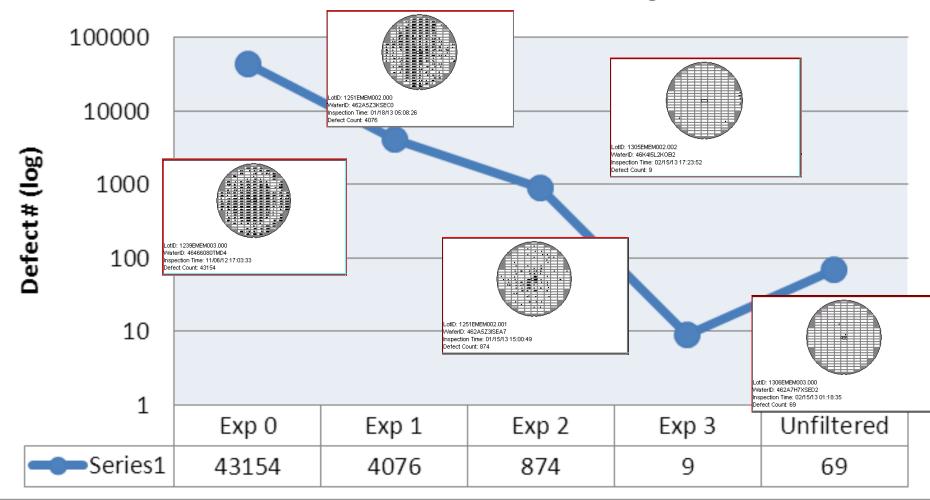












Transfer learning to other BEOL masks

Empire vs Empire II vs Intrepid

Transfer to Full Flows



- Several nodes of BEOL mask in development
- Monitor Health of Line flows for fab changes
- Defect Reduction programs

- Quick issue identification and solutions
 - Metrology
 - Cross-sections
 - ❖FA Lab
 - PLY tooling

Acknowledgements

- I would like to thank the CNSE engineering and integration team in support of continuing development
- Special regards to Dan Steinke, Corbet Johnson, and Ilyssa Wells for their work on the PLY reduction team